1. (normative)
SMT summary table - DRD
	1. DRD identification
		1. Requirement identification and source document

This DRD is called from ECSS-Q-ST-70-38, requirement 14.11a.

* + 1. Purpose and objective

The purpose of the SMT summary table is to consolidate the approval status of the boundary conditions for the verification activity.

* 1. Expected response
		1. Scope and content

The SMT summary table shall include the following data

Assembly processes

PID reference with issue

Solder type: For machine reflow and for hand assembly

Conformal coating

Substrate type: Polyimide

Device data as shown in Table H-1.

1. Examples of assembly processes are vapour phase and hand soldering or convection reflow + hand soldering or hand soldering.
	* 1. Special remarks

None.

: Device type preparation and mounting configuration

| Device family  | Package | Manufacturer | Package dimensions  | Bonding material (under device) | Stacking material (edge or corner) | Terminal material | Lead finish | Pitch(mm) | Nominal Terminal thickness (mm)/ Nominal width | In-House degolding / pretinning | In-house lead forming Yes/No/NA | Artificial stand-off Yes/No | Final report |
| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| Ceramic chip | C0603 Type 1 |  | Length, width | NA | NA |  | Sn/Pb | NA | NA | No | N/A | No |  |
| Ceramic | C0603 Type 11 |  |  |  |  |  |  |  |  |  | N/A |  |  |
| Ceramic resistor | R0805 |  |  | NA | NA |  | Sn/Pb | NA | NA | No | N/A | No |  |
| Diode | D5-B |  |  |  |  |  |  |  |  |  | N/A |  |  |
| Tantalum capacitors |  |  |  |  |  |  |  |  |  |  |  |  |  |
| IC | FP10 Bottom brazed |  |  | yes | One the side | Alloy42 | Gold | 1,27 | 0,25 | yes | yes | NA |  |
| CQFP | CQFP196 top brazed |  |  |  |  | Kovar |  |  |  |  | No |  |  |